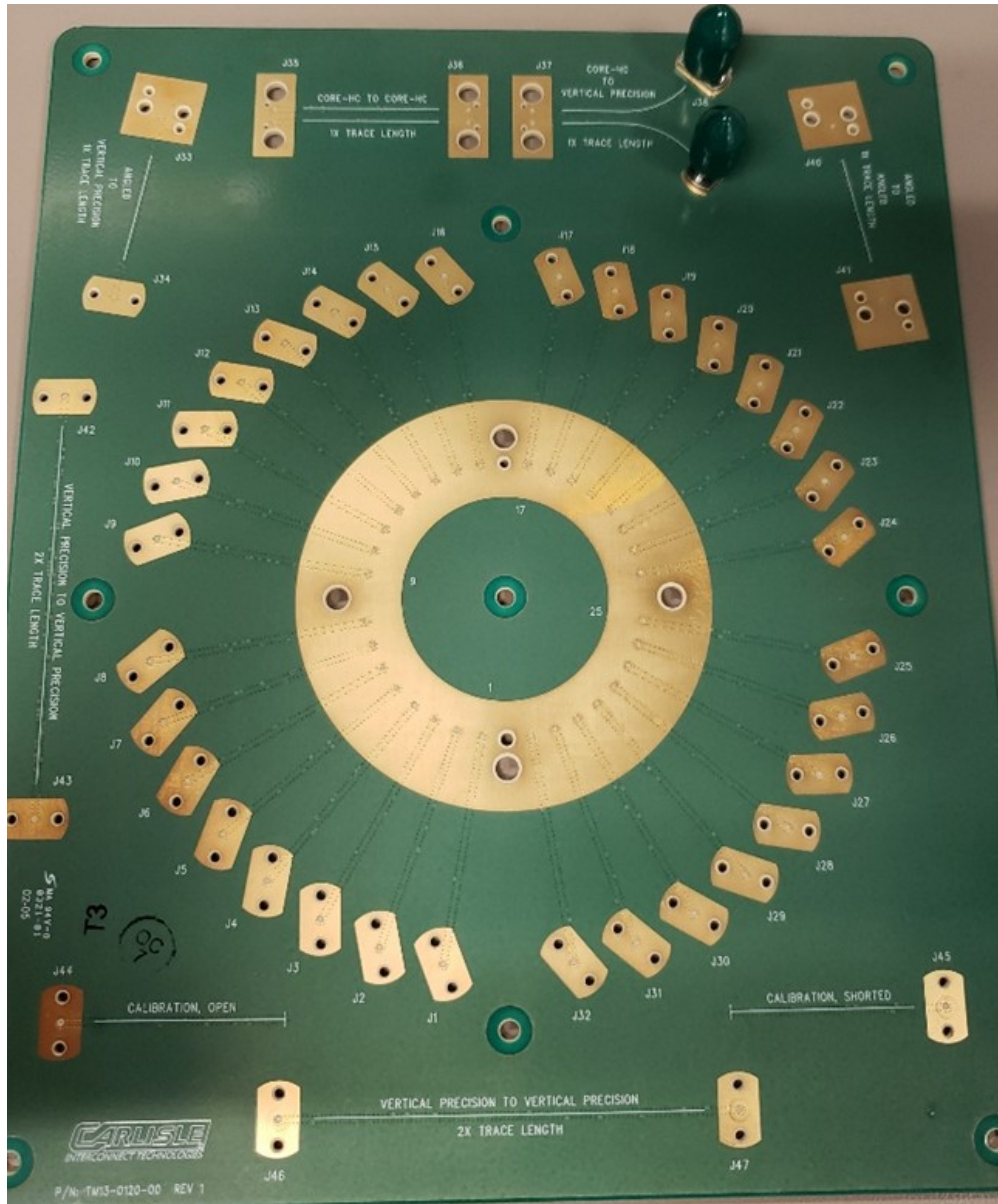


SIGNAL INTEGRITY REPORT

Test and Measurement Performance Report

Part Number TM7SSSH22S8MS028 (Core HC)

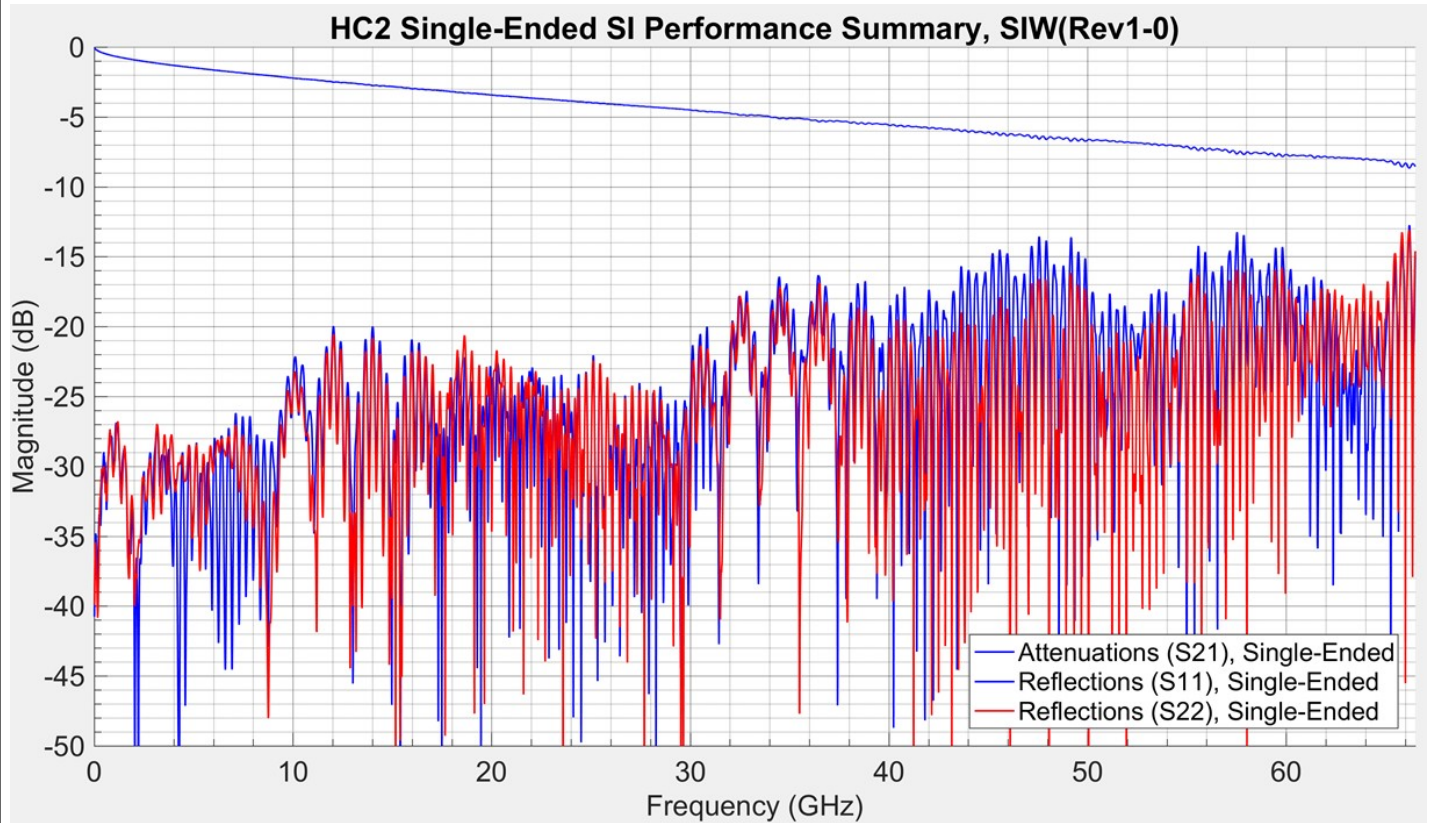
Distribution: Internal and External Use



<u>REVISION:</u> 1	<u>ECN INFORMATION:</u> EC No: N/A DATE: 04/12/2021	<u>TITLE:</u> Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	<u>SHEET No.</u> 1 of 21
<u>DOCUMENT NUMBER:</u> RSI-TM7SSSH22S8MS028	<u>SI ENGINEER:</u> R.Stavoli	<u>DESIGN ENGINEER</u> H.Tran	<u>ENGINEERING MANAGER</u> E.Soubh
<small>TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC</small>			

SIGNAL INTEGRITY REPORT

SI Performance Summary (Attenuation & Reflections, Substrate Integrated Waveguide/SIW, Single-Ended)



* For further details regarding the testing setup and configuration please see the rest of the report.

<u>REVISION:</u> 1	<u>ECN INFORMATION:</u> EC No: N/A DATE: 04/ 12 / 2021	<u>TITLE:</u> Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	<u>SHEET No.</u> 2 of 21
<u>DOCUMENT NUMBER:</u> RSI-TM7SSSH22S8MS028		<u>SI ENGINEER:</u> R.Stavoli	<u>DESIGN ENGINEER</u> H.Tran
		<u>ENGINEERING MANAGER</u> E.Soubh	
<small>TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC</small>			

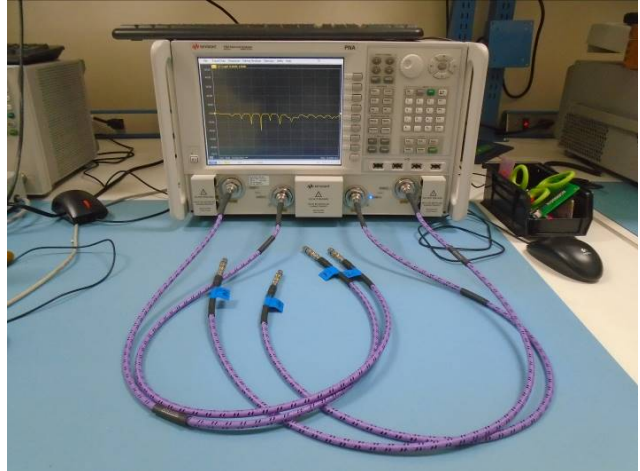
SIGNAL INTEGRITY REPORT

1.0 TEST SETUP AND DUT

Equipment, fixtures, and methods

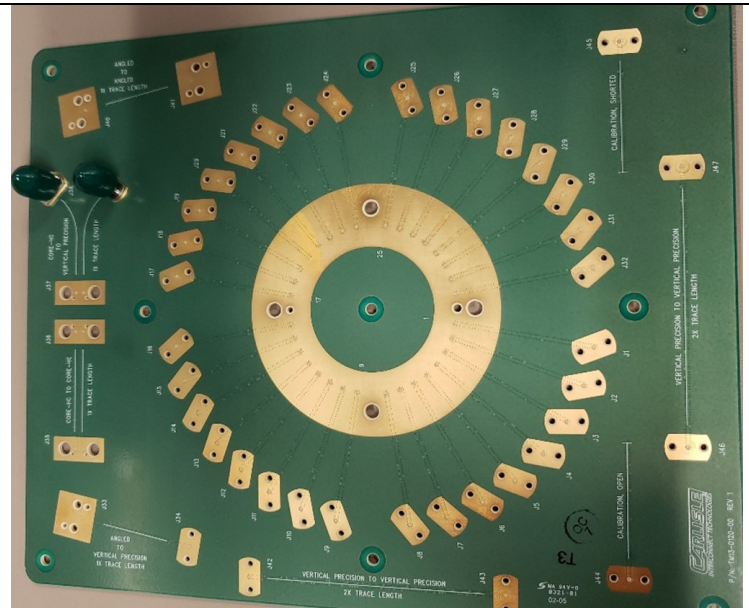
Test method: All data measured from test PCB shown below and a N5227A PNA Network Analyzer

- Calibration was performed up to the 1.85mm SMA adapters using calibration kit: 85058B
- Data was swept from 10 MHz to 67GHz for 6700 points
- Data averaging was turned off.
- Data is not dembedded and includes the board traces and the Core HC cable assembly



Assembly Description

- T&M PN: TM7SSSH22S8MS028
- 2- Position LCP Connector Housing, two pieces at the interface
- **11-inch solid center conductor 092 coax cable**
- Carlisle DUT PCB: TM13-0120-00
Core HC 32-position eval board, SIW, Vertical Launch, **Rev 1, #0**
- Port 1: 1.85mm Cable Connector (Core HC)
- Port 2: 1.85mm Cable Connector (Core HC) or 1.85mm Stripline Vertical Launch Precision Connector (on HC2, SIW PCB)



Testing Samples:

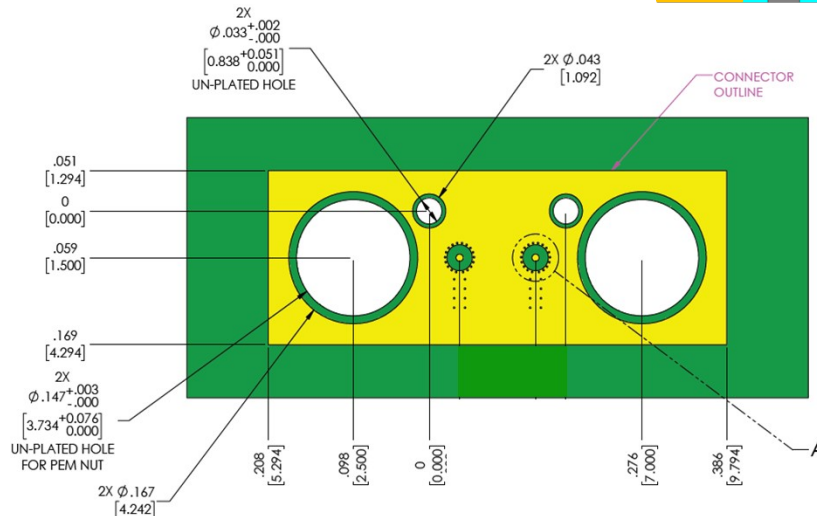
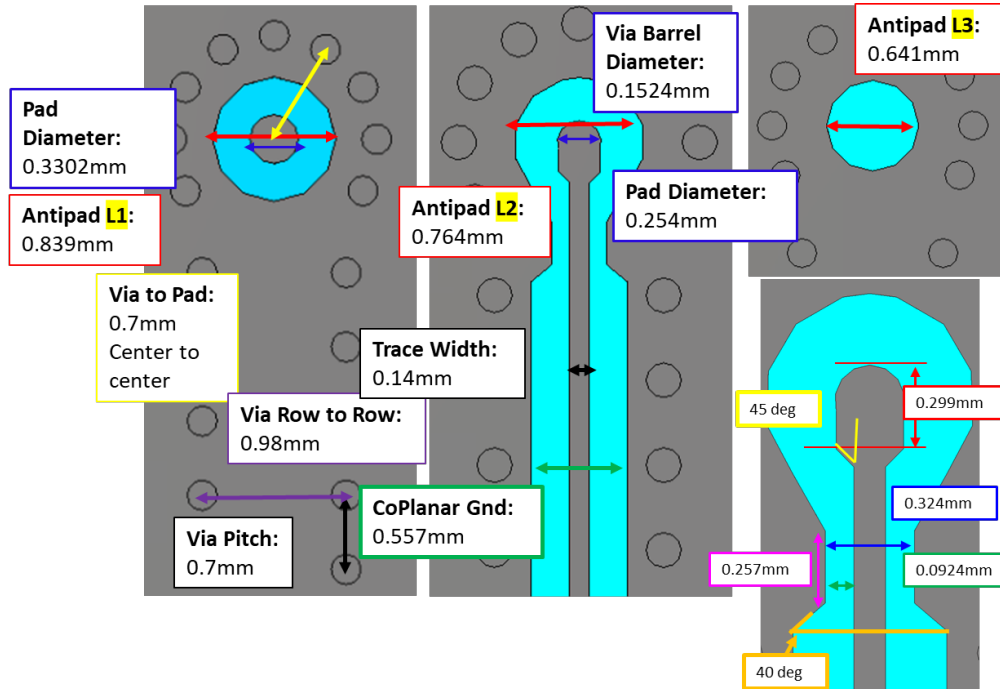
- 4 Samples
- 4 Channels
- 2 THRU Measurements w/ PCB, Core HC2 → Core HC2
- 2 Crosstalk Meas. w/PCB (FEXT, NEXT), HC2 → HC2
- 1 THRU Measurements w/ PCB, HC2 → 1.85mm Vertical Precision Connector
- 2 THRU Meas. w/RF Adaptor (2 Chan. x 1 samples)

REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/12/2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 3 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1)DOC			

SIGNAL INTEGRITY REPORT

2.0 BOARD STACKUP & FOOTPRINT INFORMATION

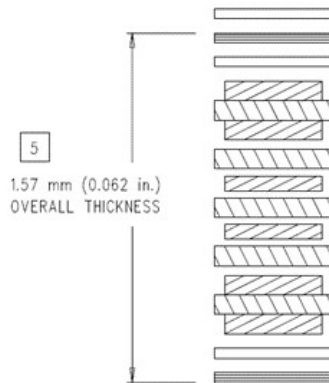
- TM13-0120-00 Carlisle Core HC 32-Position, SIW Test Board
 - Revision 1, #0, Substrate Integrated Waveguide(SIW), Vertical Launch
 - **Cable Assembly placed on 2-Position Single-Ended Footprint**
- Dielectric Material: Tachyon 100G (Dk.2.98, Df 0.0015 @ 20 GHz)
 - L1 Core Thickness: L1: 0.127mm / 5 mil
 - L2 PrePreg Thickness: L2: 0.149mm / 5.9mil
 -



REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/ 12 / 2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 4 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

6 LAYER BOARD
LAYER STACKUP DETAIL



LYR	NAME	TYPE	MATERIAL	THICKNESS	NOTES
		SILKSCREEN			
		SURFACE FINISH	ENIG		
		SOLDER MASK			0.02 mm (0.001 in) THICK
1	TOP	COPPER FOIL	VLP-2	0.041 mm (0.0016 in)	THICKNESS INCLUDES PLATING AND SURFACE FINISH
		CORE	TACHYON 100G	0.127 mm (0.0049 in)	Dk 2.98 / Df 0.0015
2	LAYER 2	COPPER FOIL	VLP-2	0.015 mm (0.0006 in)	1/2 oz.
		PREPREG	TACHYON 100G	0.147 mm (0.0058 in)	Dk 3.19 / Df 0.0021
3	LAYER 3	COPPER FOIL	VLP-2	0.015 mm (0.0006 in)	1/2 oz.
		PREPREG or CORE	TACHYON 100G	A/R TO MEET OVERALL THICKNESS	DIELECTRIC
4	LAYER 4	COPPER FOIL	VLP-2	0.015 mm (0.0006 in)	1/2 oz.
		PREPREG	TACHYON 100G	0.147 mm (0.0058 in)	Dk 3.19 / Df 0.0021
5	LAYER 5	COPPER FOIL	VLP-2	0.015 mm (0.0006 in)	1/2 oz.
		CORE	TACHYON 100G	0.127 mm (0.0049 in)	Dk 2.98 / Df 0.0015
6	BOTTOM	COPPER FOIL	VLP-2	0.041 mm (0.0016 in)	THICKNESS INCLUDES PLATING AND SURFACE FINISH
		SOLDER MASK			0.02 mm (0.001 in) THICK
		SURFACE FINISH	ENIG		

C) PCB FINISH

1. Surface Protective Plating

- All exposed copper on the outer layers shall be plated with a protective surface finish.
- All exposed pads, edge fingers and plated through holes shall be ENIG with thickness listed in Table 2.

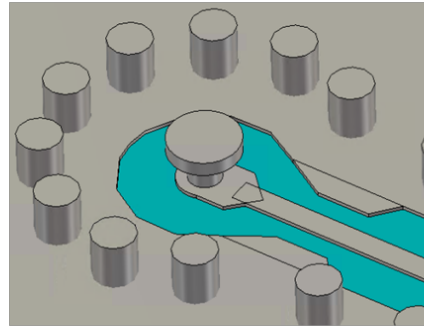
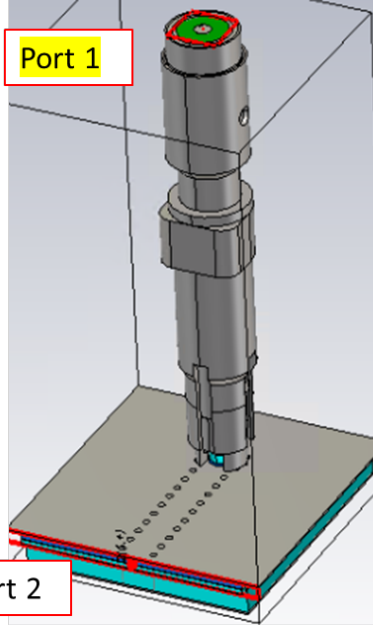
Table 2: Protective Plating Thickness

Nickel		Immersion Gold	
µm (microinch)		µm (microinch)	
Min.	Max.	Min.	Max.
2.5 (100)	13(512)	0.051 (2)	0.2032 (8)

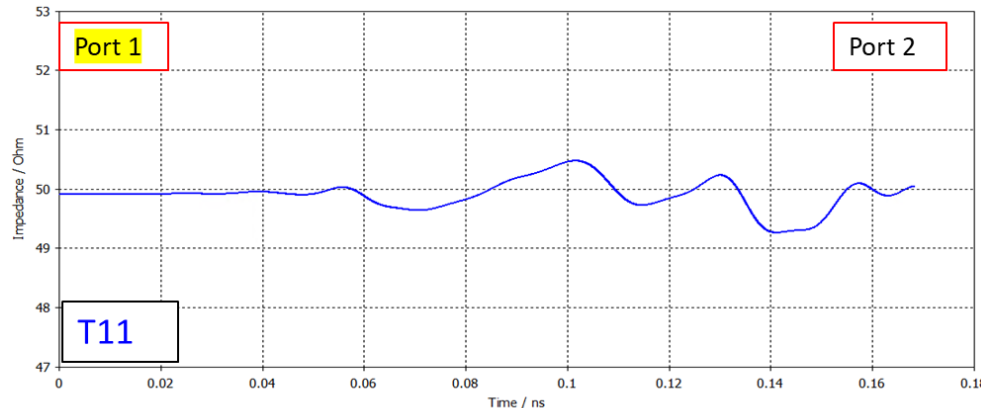
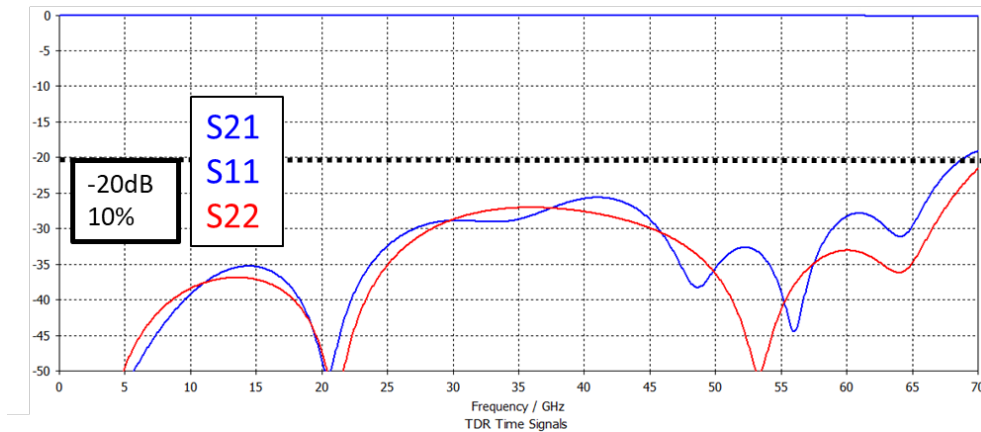
REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/12/2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 5 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

3.0 SIMULATION RESULTS, SUBRTRATE INTEGRATED WAVEGUIDE, SINGLE-ENDED



Diameter:
 Signal Pad (L1): 0.3302mm/13mil
 Antipad (L1): 0.839mm/33.07mil
 Signal Pad (L2): 0.254mm/10mil
 Finish Via: 0.1524mm/6mil

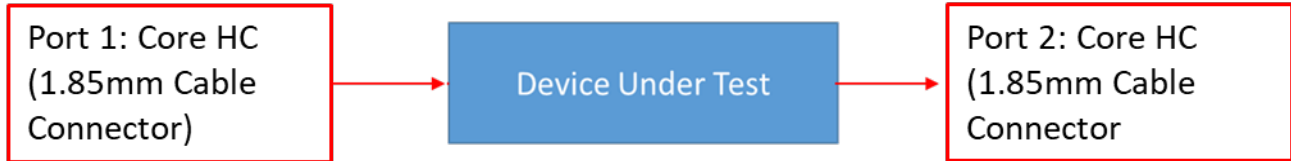


HC2_Stripline_QualRing+StandardHC_FullAssy-6L_Core5mil_Preg5.8mil_Via6mil_P1_HC2_P2_PCB_AddTuning_424_Rev_2.s2p 10/26/2020 6:25 PM S2P File 147 KB

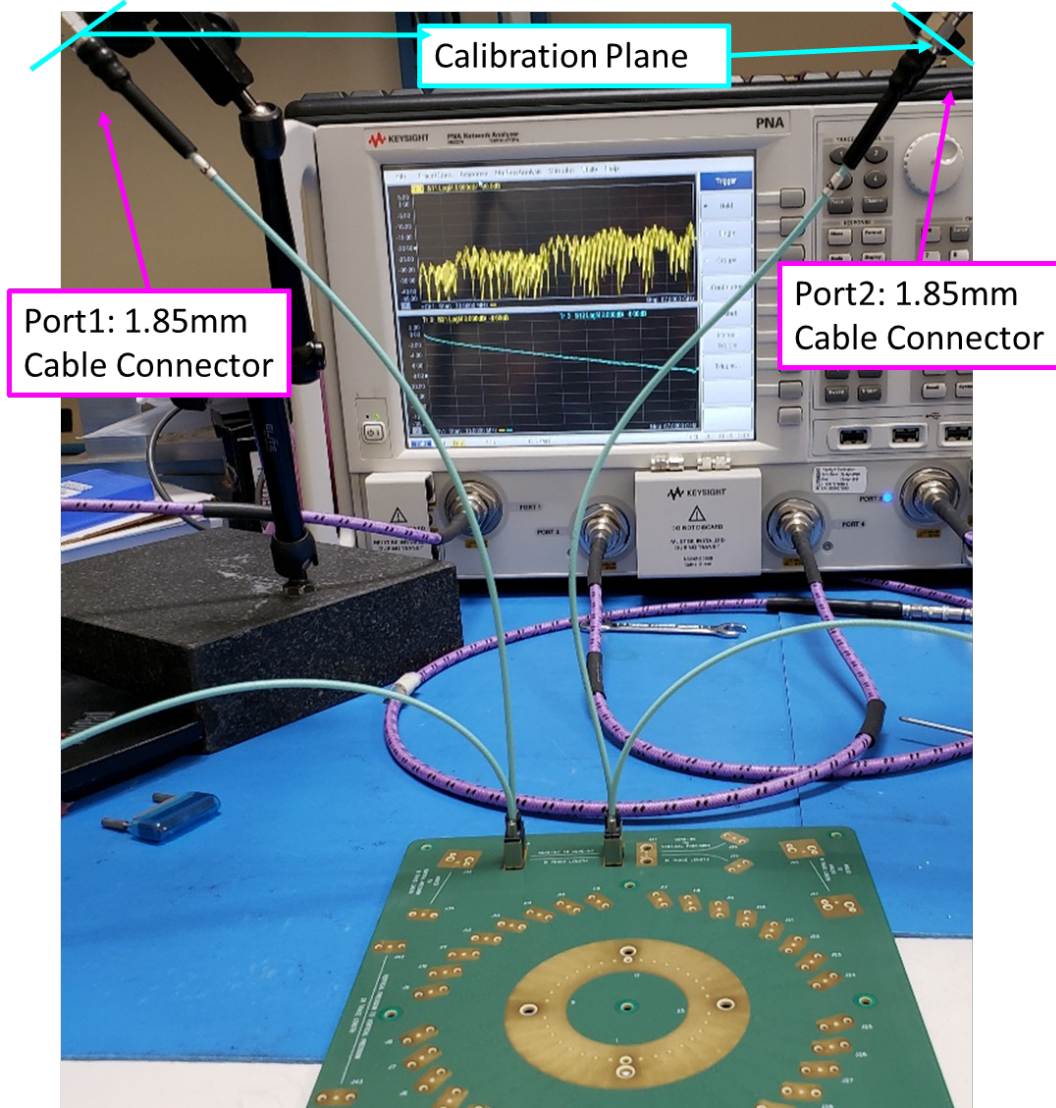
REVISION: <p style="font-size: 2em; font-weight: bold;">1</p>	ECN INFORMATION: EC No: N/A DATE: 04/12/2021	TITLE: <p style="font-size: 1.2em; font-weight: bold;">Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB)</p> <p style="font-weight: bold;">CARLISLE IT CONFIDENTIAL</p>	SHEET No. <p style="font-size: 1.2em; font-weight: bold;">6 of 21</p>
DOCUMENT NUMBER: <p style="font-size: 1.2em; font-weight: bold;">RSI-TM7SSSH22S8MS028</p>	SI ENGINEER: <p style="font-weight: bold;">R.Stavoli</p>	DESIGN ENGINEER <p style="font-weight: bold;">H.Tran</p>	ENGINEERING MANAGER <p style="font-weight: bold;">E.Soubh</p>
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

4.0 MEASUREMENT SET-UP, CORE HC2 → HC2, SINGLE-ENDED (HC2 SIW REV1 PCB)

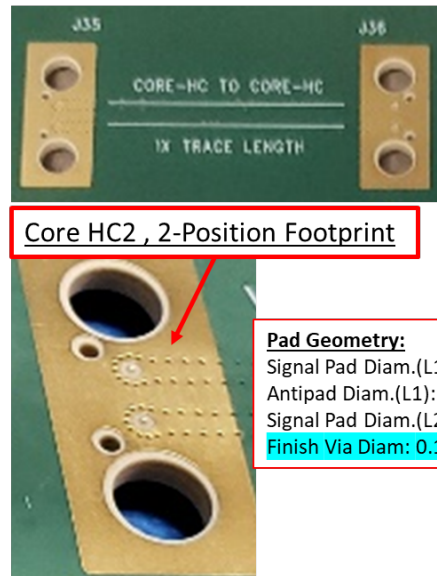
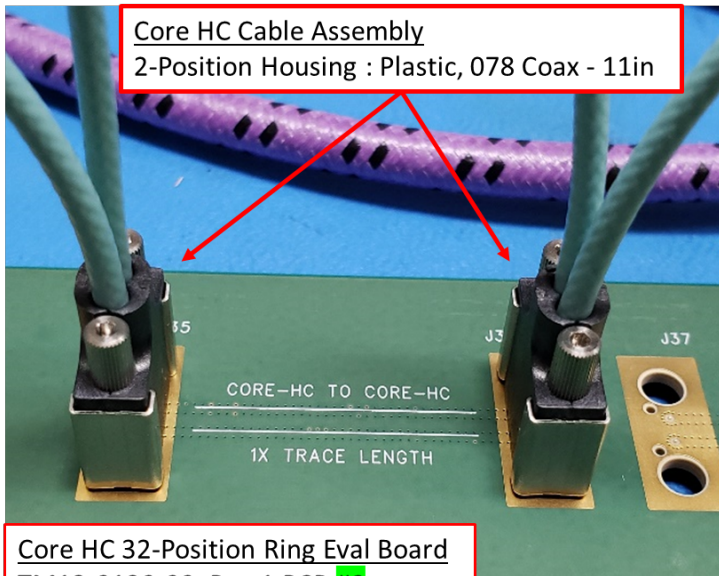


Measurements are not dembedded and include the **Core HC assemblies** (cable connector, cable, interconnect), PCB (transitions, traces)



<u>REVISION:</u> 1	<u>ECN INFORMATION:</u> EC No: N/A DATE: 04/12/2021	<u>TITLE:</u> Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	<u>SHEET No.</u> 7 of 21
<u>DOCUMENT NUMBER:</u> RSI-TM7SSSH22S8MS028	<u>SI ENGINEER:</u> R.Stavoli	<u>DESIGN ENGINEER</u> H.Tran	<u>ENGINEERING MANAGER</u> E.Soubh
<small>TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC</small>			

SIGNAL INTEGRITY REPORT



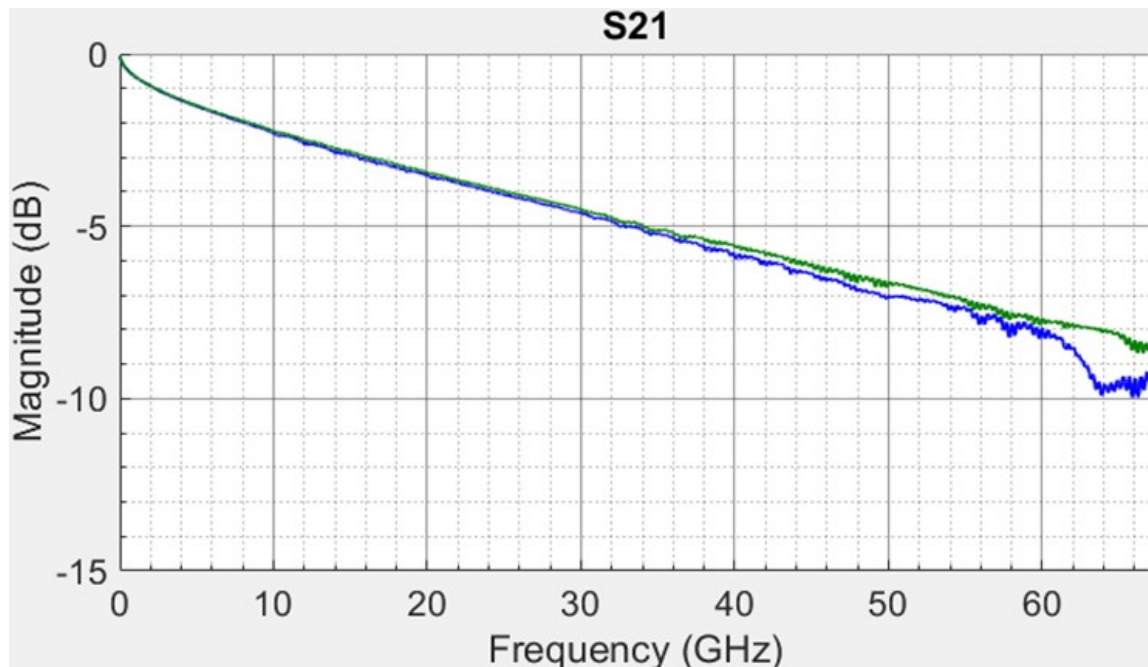
Pad Geometry:
Signal Pad Diam.(L1): 0.3302mm/13mil
Antipad Diam.(L1): 0.839mm/33.07mil
Signal Pad Diam.(L2): 0.254mm /10mil
Finish Via Diam: 0.1524mm/6mil

Core HC 32-Position Ring Eval Board
TM13-0120-00, Rev 1, PCB #0

5.0 SIGNAL INTEGRITY RESULTS, SINGLE-ENDED (HC2 SIW REV1 BOARD)

Insertion Loss (S21), Single-Ended

(CoreHC Channels: 3→4 & 11 → 2, Board Locations: J35, J36)

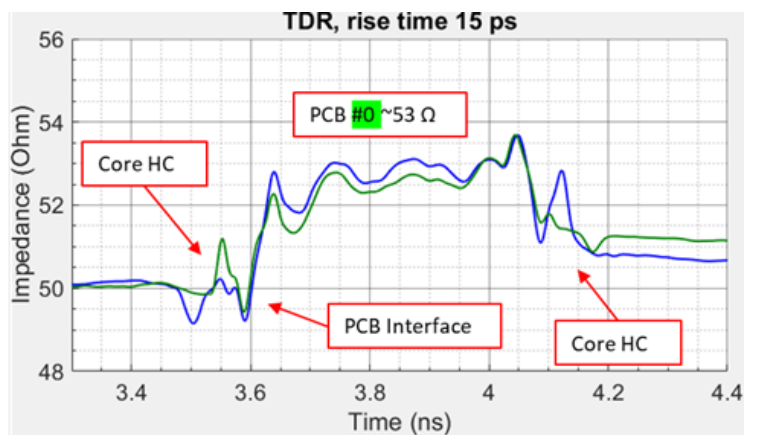
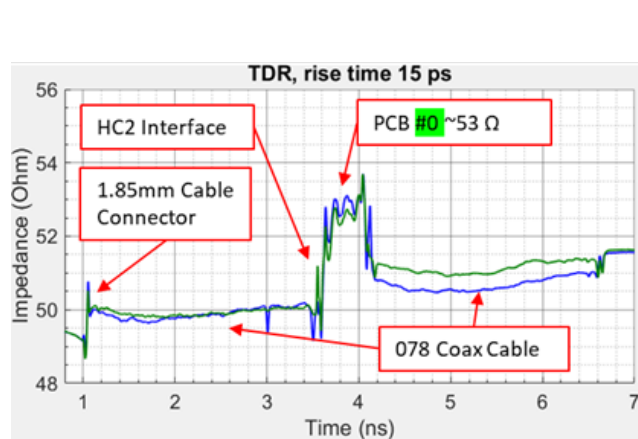
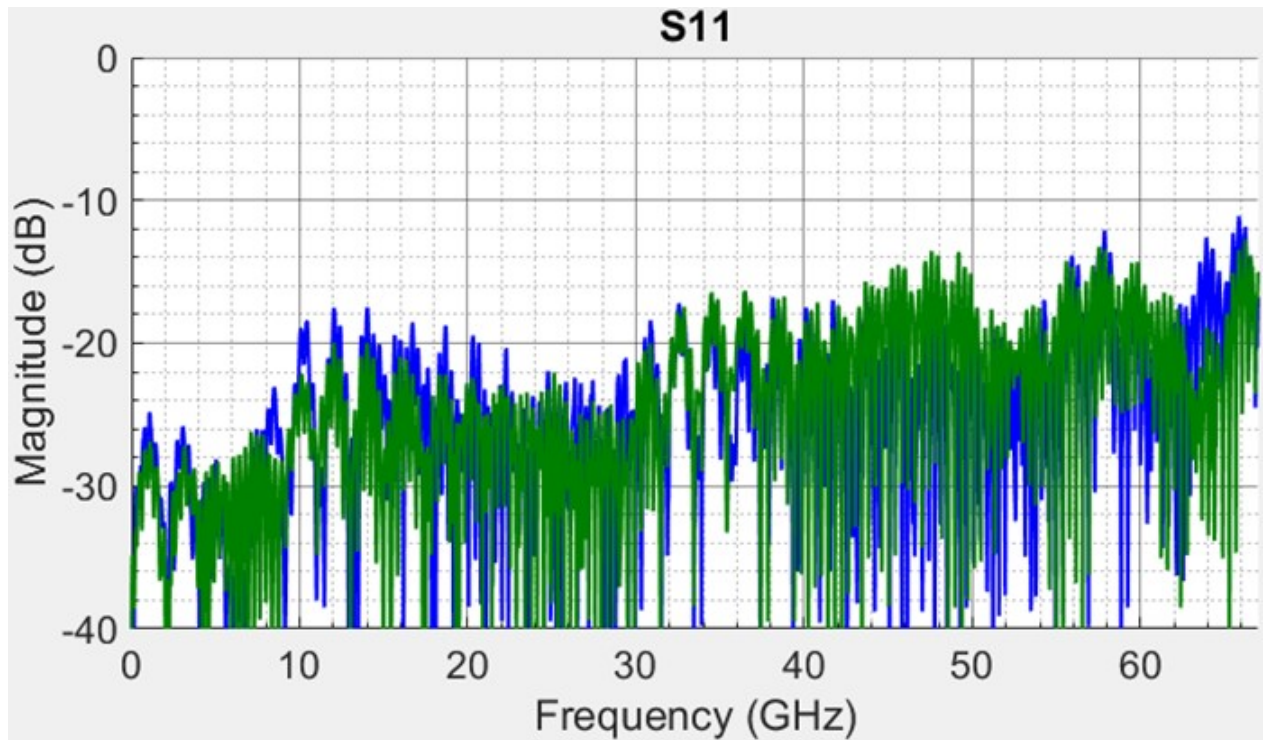


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DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

Return Loss (S11), Single-Ended

(CoreHC Channels: 3→4 & 11 → 2, Board Locations: J35, J36)



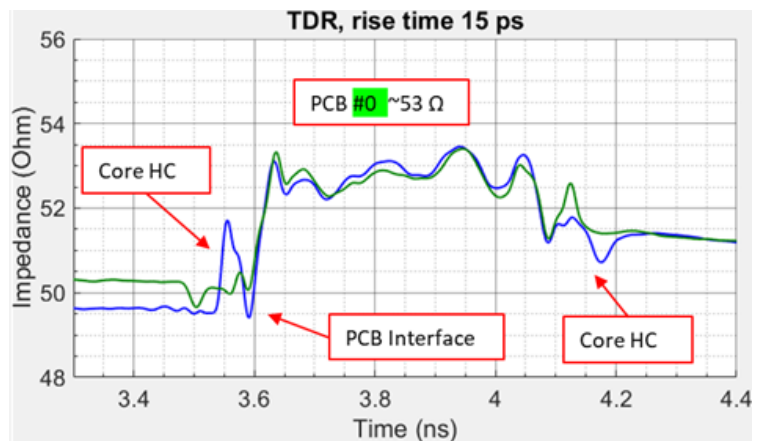
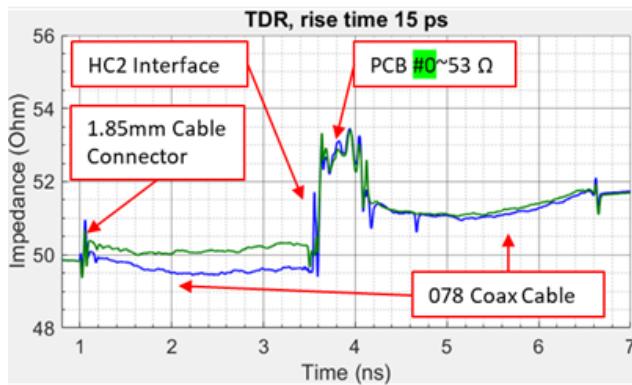
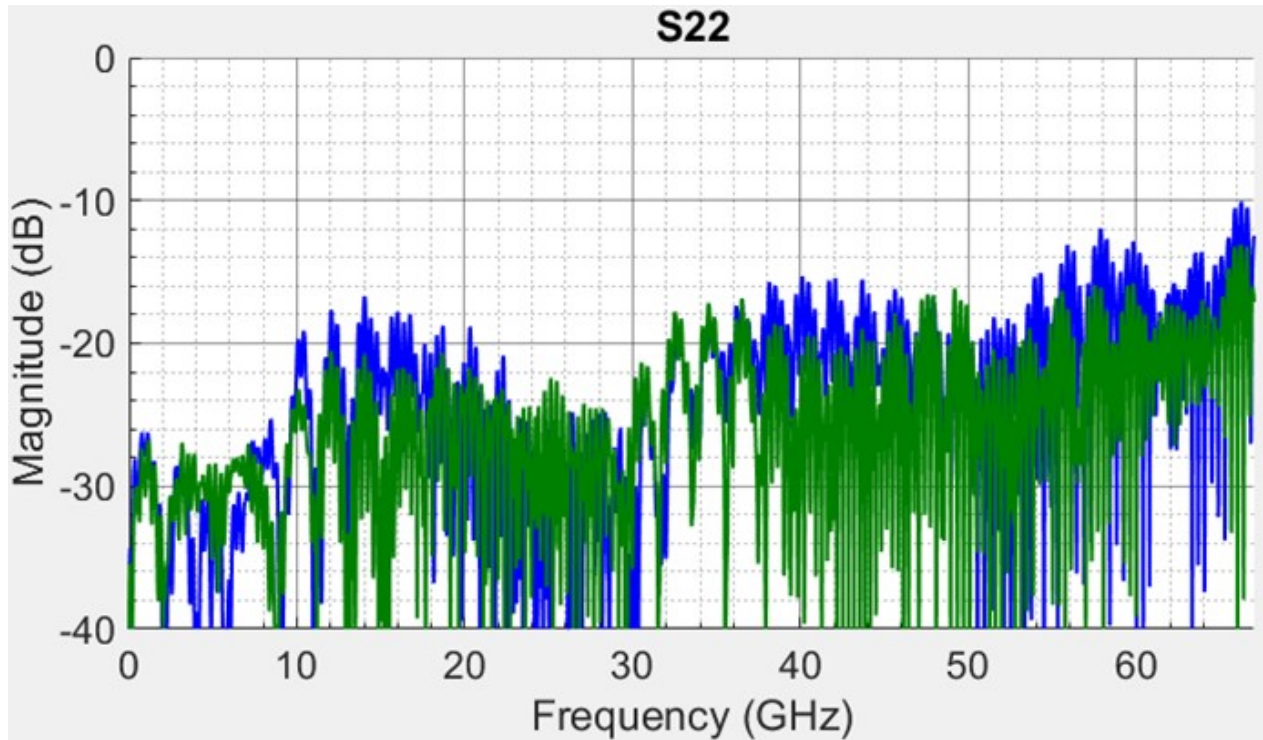
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DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
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SIGNAL INTEGRITY REPORT

Return Loss (S22), Single-Ended

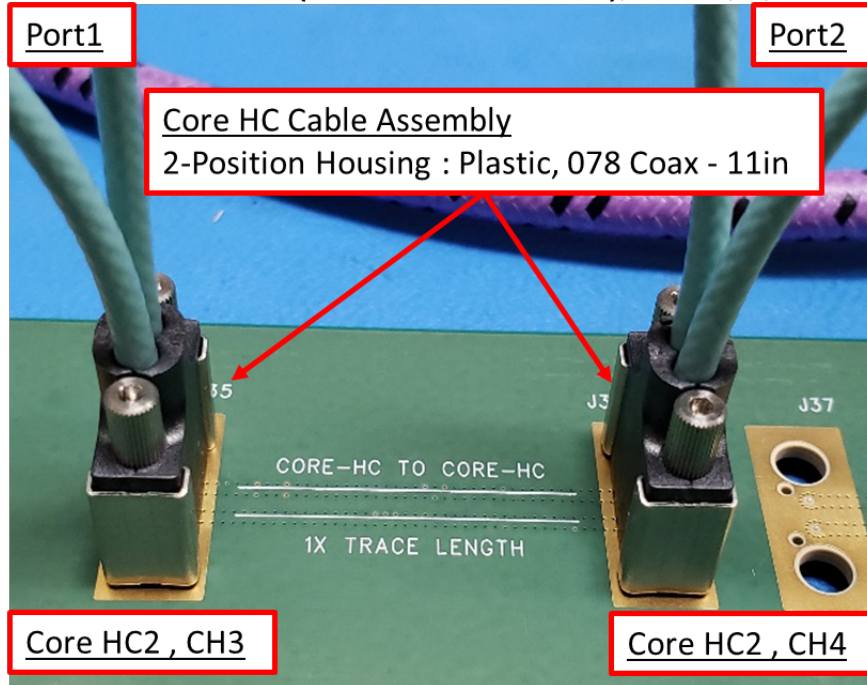
(CoreHC Channels: 3→4 & 11 → 2, Board Locations: J35, J36)



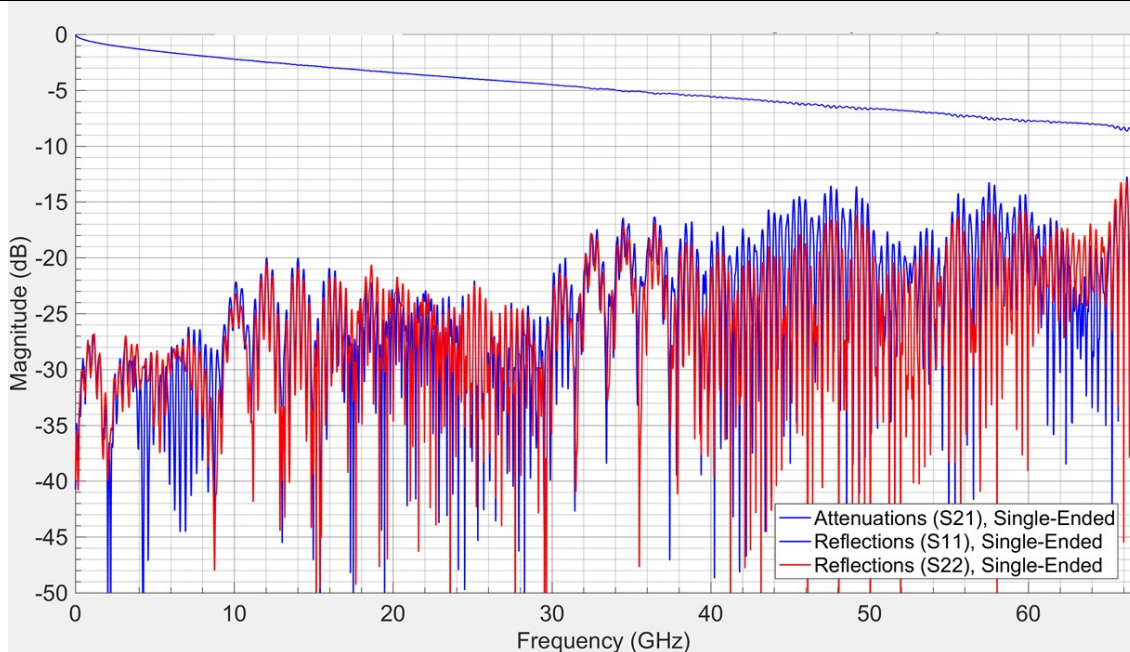
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DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER: H.Tran	ENGINEERING MANAGER: E.Soubh

SIGNAL INTEGRITY REPORT

6.0 SIGNAL INTEGRITY RESULTS (HC2 SIW REV1 PCB), CH #3, 4, LOCATION J35-36



Insertion(S21) and Return (S11, S22) Loss, Single-Ended (CoreHC Channel: 3 → 4, Board Location: J35 → J36)

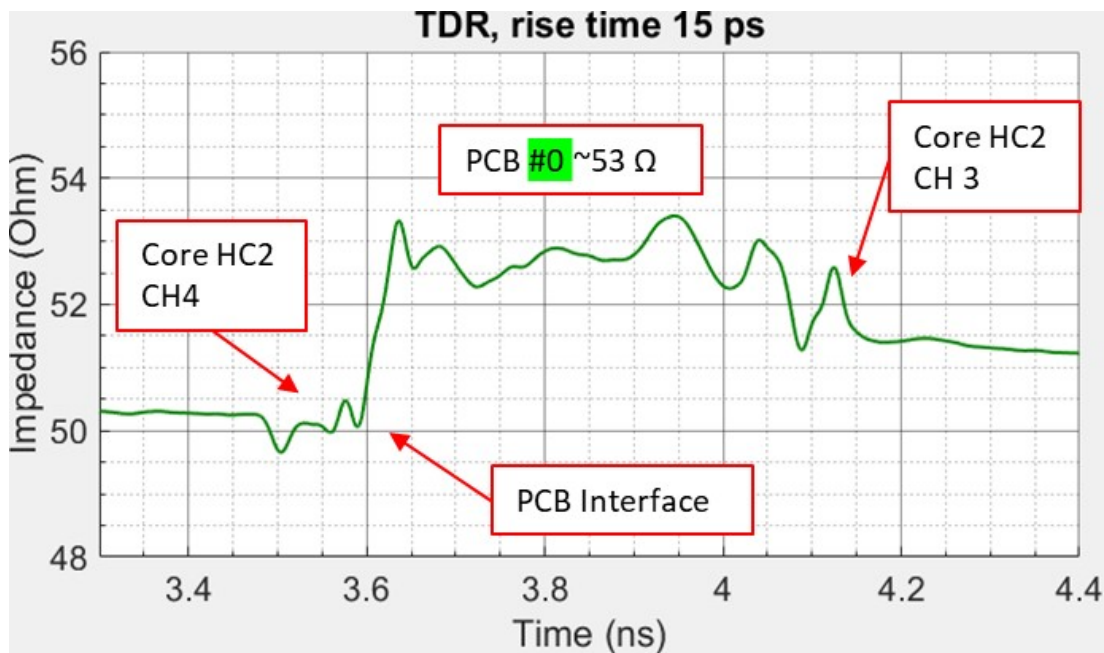
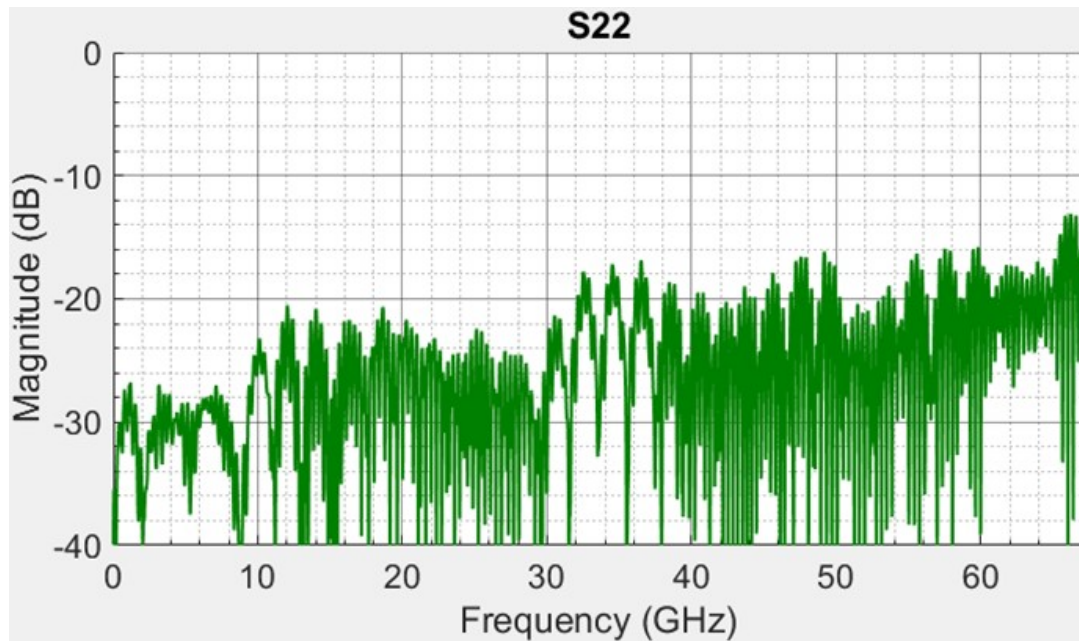


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DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

Return Loss (S22), Single-Ended

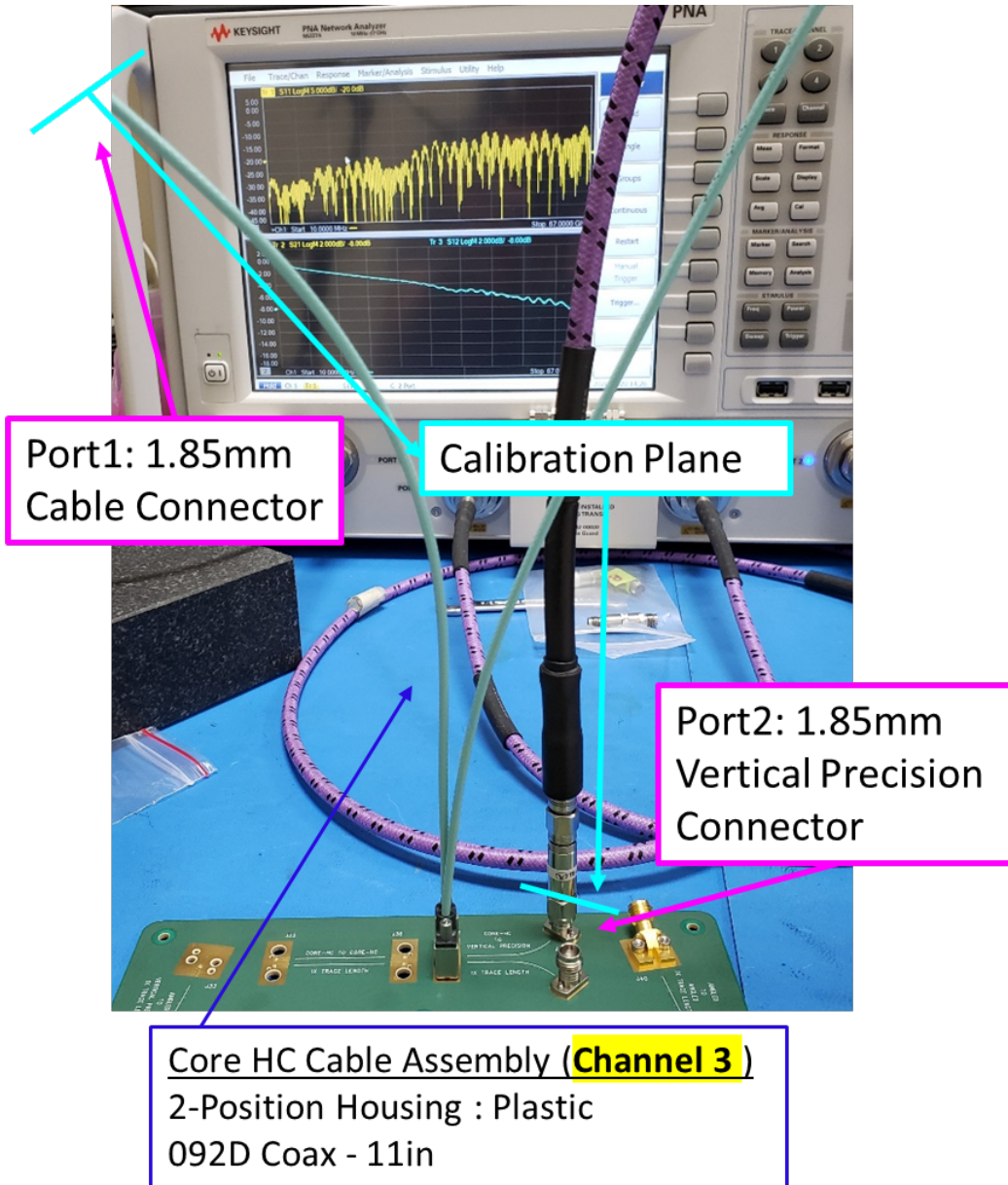
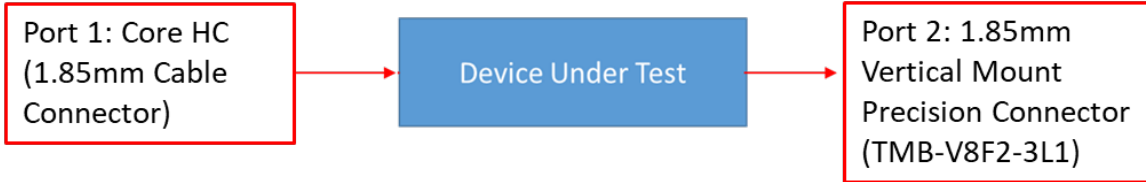
(CoreHC Channel: 3 → 4, Board Location: J35 → J36)



REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/12/2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 12 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
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SIGNAL INTEGRITY REPORT

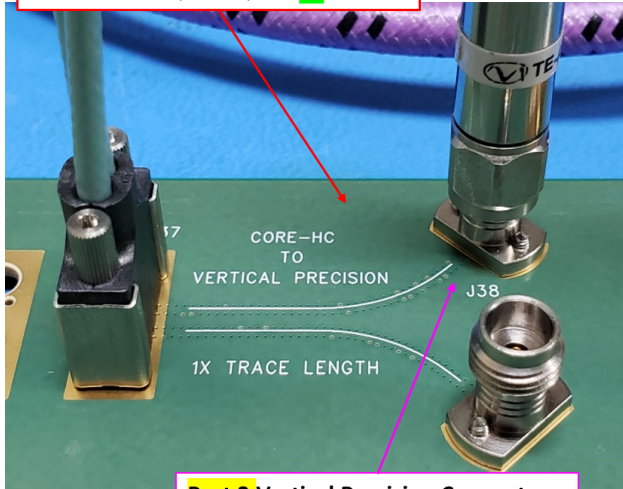
7.0 MEASUREMENT SET-UP, DE-EMBEDDING: CORE HC → 1.85 VERTICAL PREC. CONNECTOR



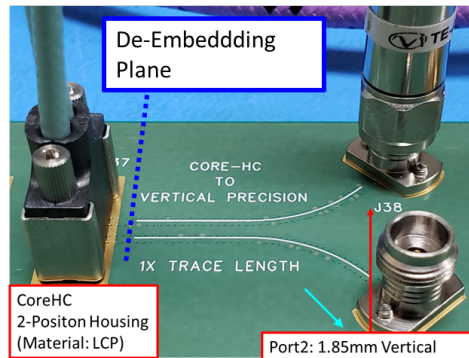
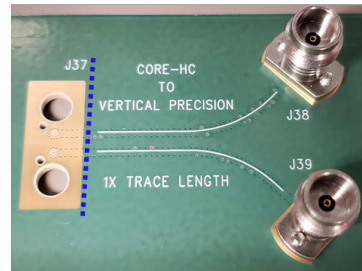
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DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh

SIGNAL INTEGRITY REPORT

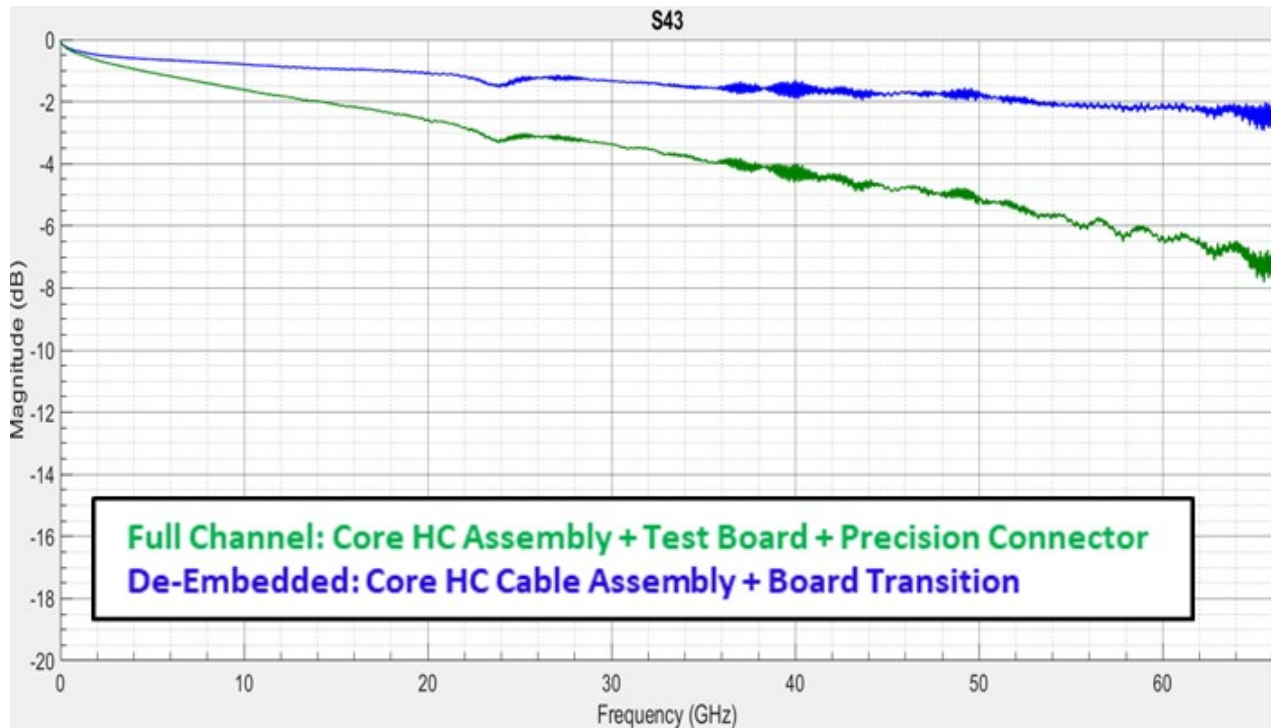
Core HC 32-Position Ring Eval Board
TM13-0120-00, Rev 1, PCB #0



Port 2 Vertical Precision Connector:
1.85mm, Vertical Mount
P/N: TMB-V8F2-3L1



Insertion Loss (S21), Single-Ended (CoreHC Channels: 3, Board Locations: J39)

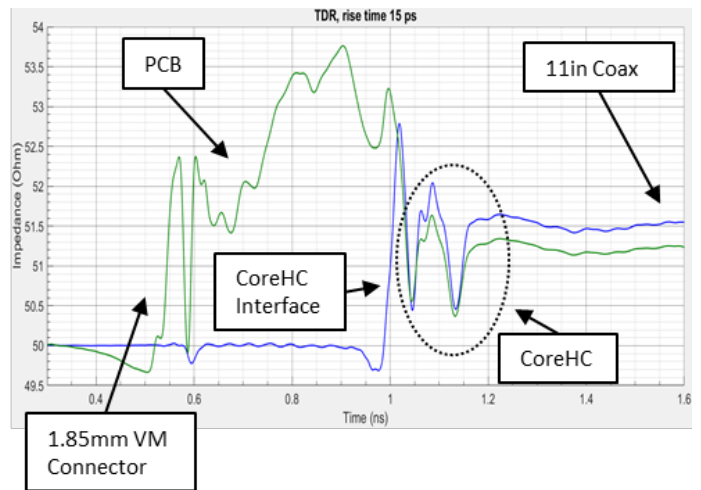
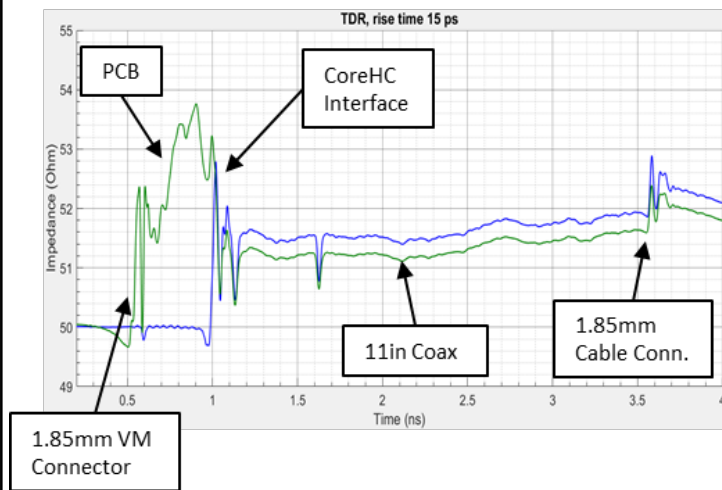
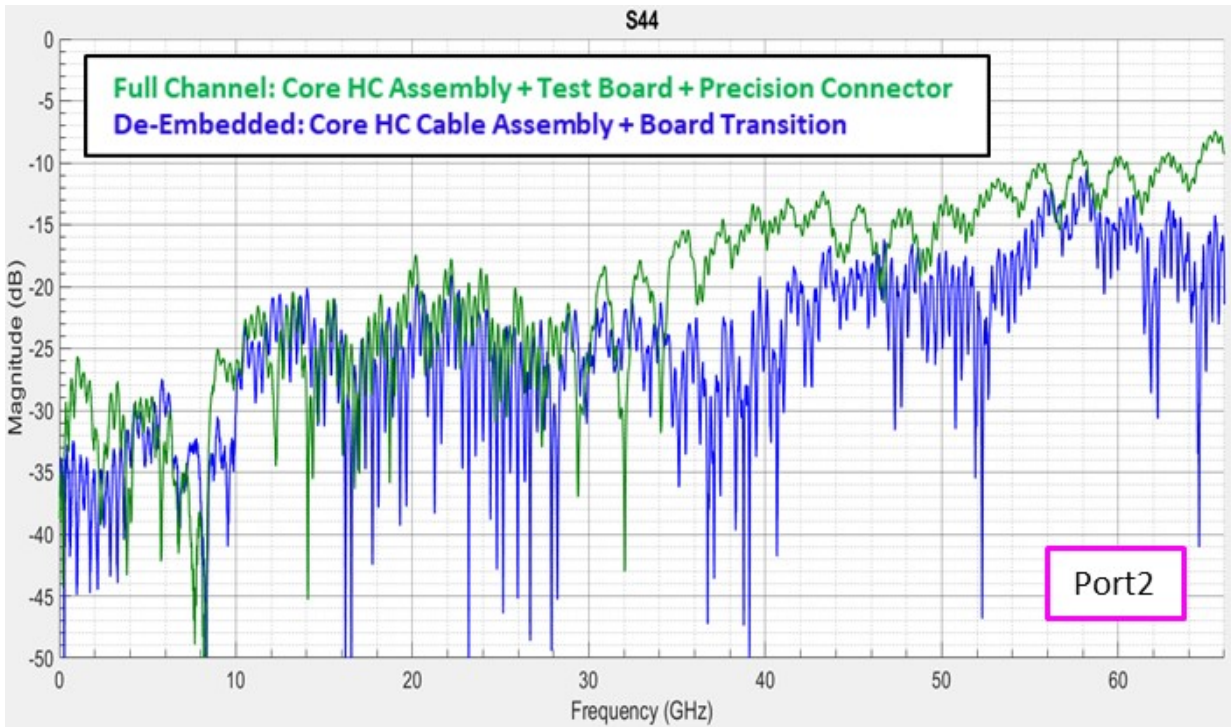


REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/ 12 / 2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 14 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

Return Loss (S22), Single-Ended

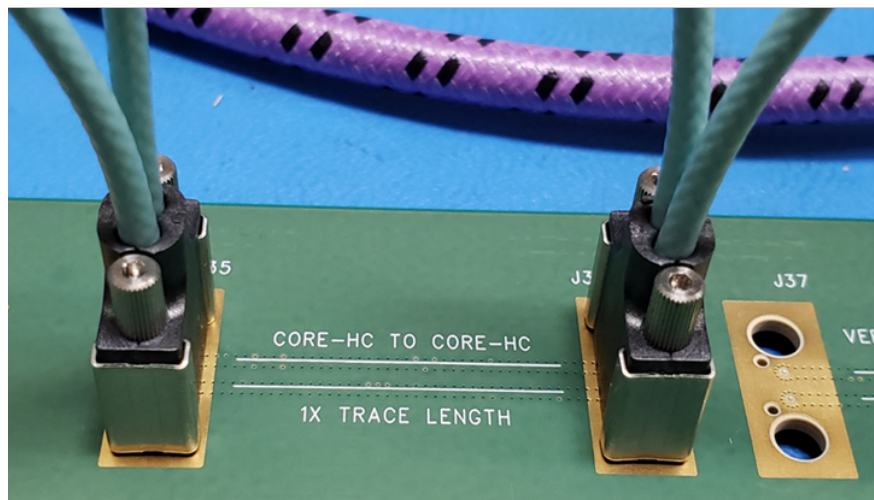
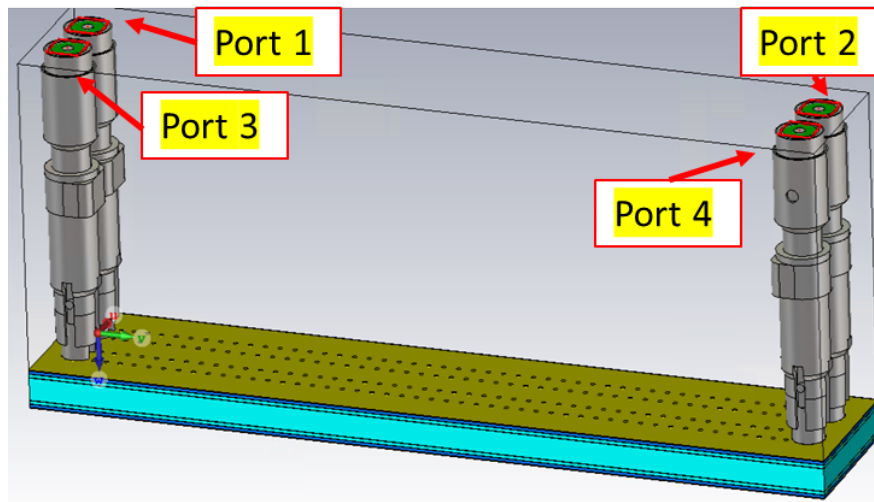
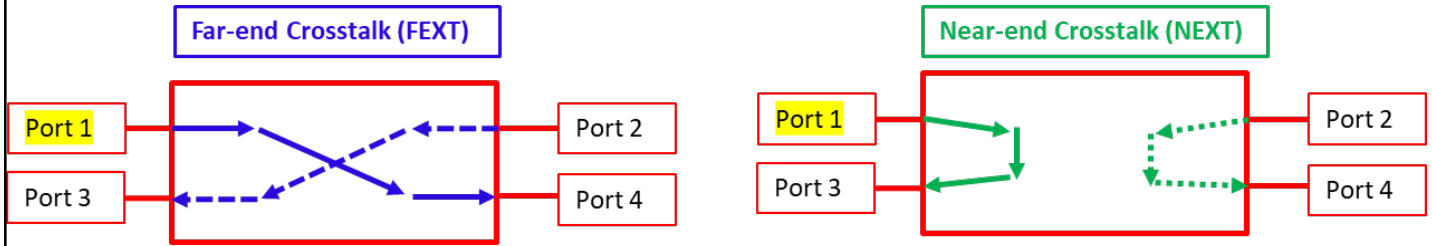
(CoreHC Channels: 3, Board Locations: J39)



REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/12/2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 15 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

8.0 MEASUREMENT SET-UP, SINGLE-ENDED, CROSSTALK (HC2 SIW REV1)



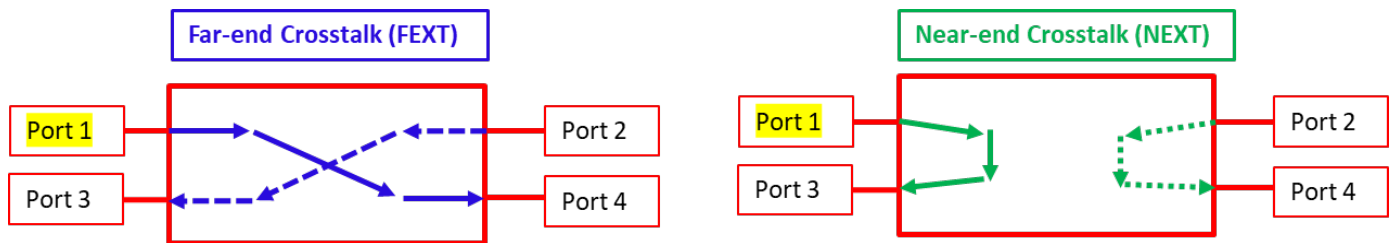
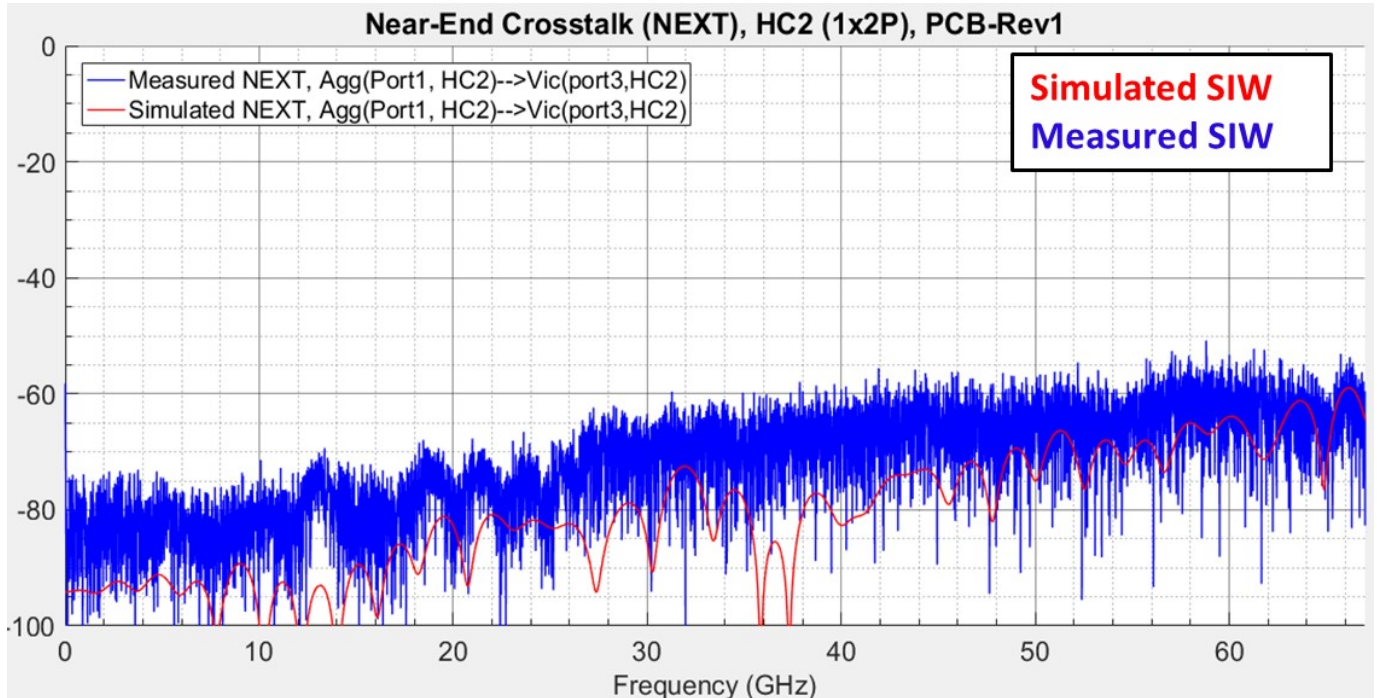
REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/ 12 / 2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 16 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

9.0 SIGNAL INTEGRITY RESULTS, SINGLE-ENDED, CROSSTALK (HC2 SIW REV1)

Near-End Crosstalk (S31), Single-Ended

(CoreHC Channels: 3, 11, Board Locations: J35), Port1(HC2-CH11) → Port3(HC2-CH3)

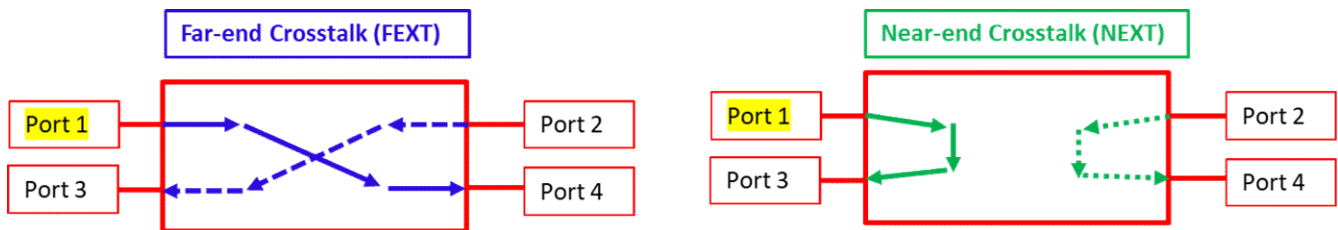
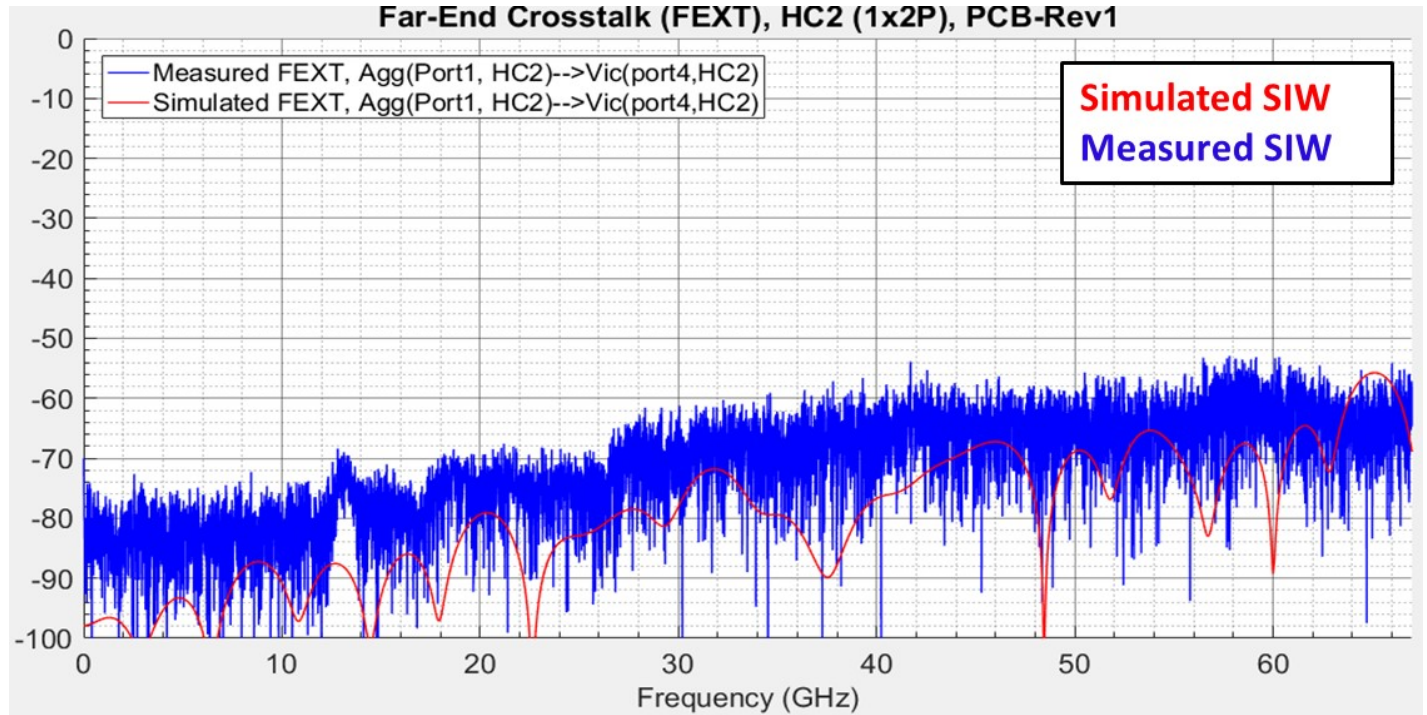


REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/ 12 / 2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 17 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
<small>TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC</small>			

SIGNAL INTEGRITY REPORT

Far-End Crosstalk (S41), Single-Ended

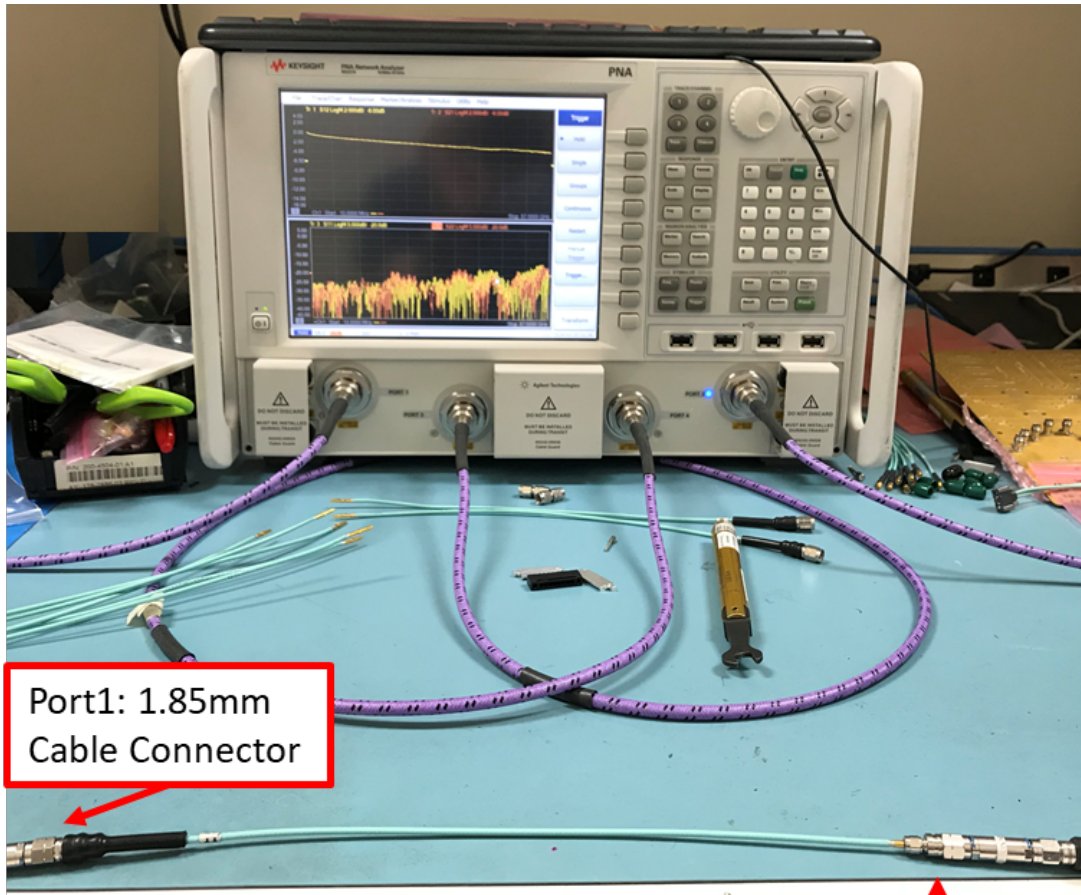
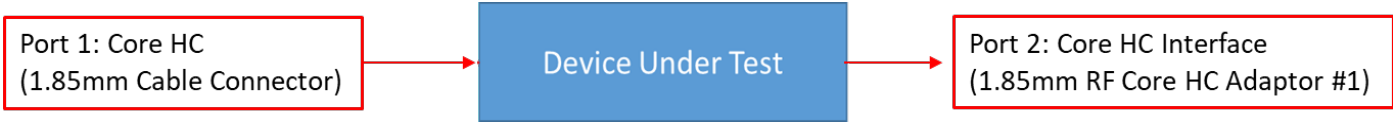
(CoreHC Channels:11, Board Locations: J35/J36), Port1(HC2-CH11) → Port 4 (VMSIW/PCB)



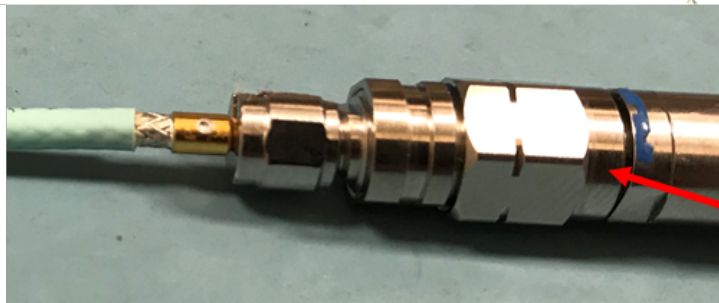
REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/ 12 / 2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 18 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

10.0 MEASUREMENT SET-UP (HC2 1.85MM RF ADAPTOR #1)



Port1: 1.85mm Cable Connector

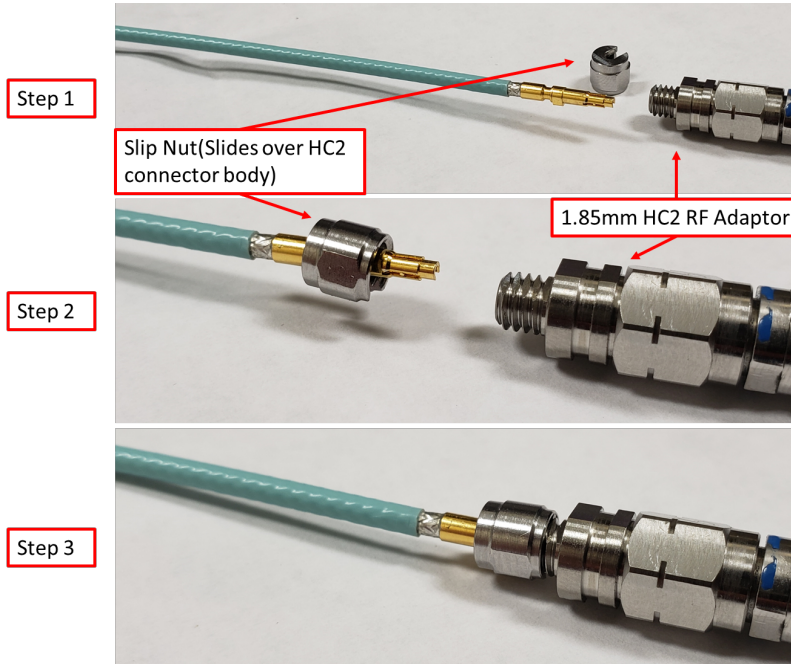


Port2: 1.85mm CoreHC Adaptor

REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/ 12 / 2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 19 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

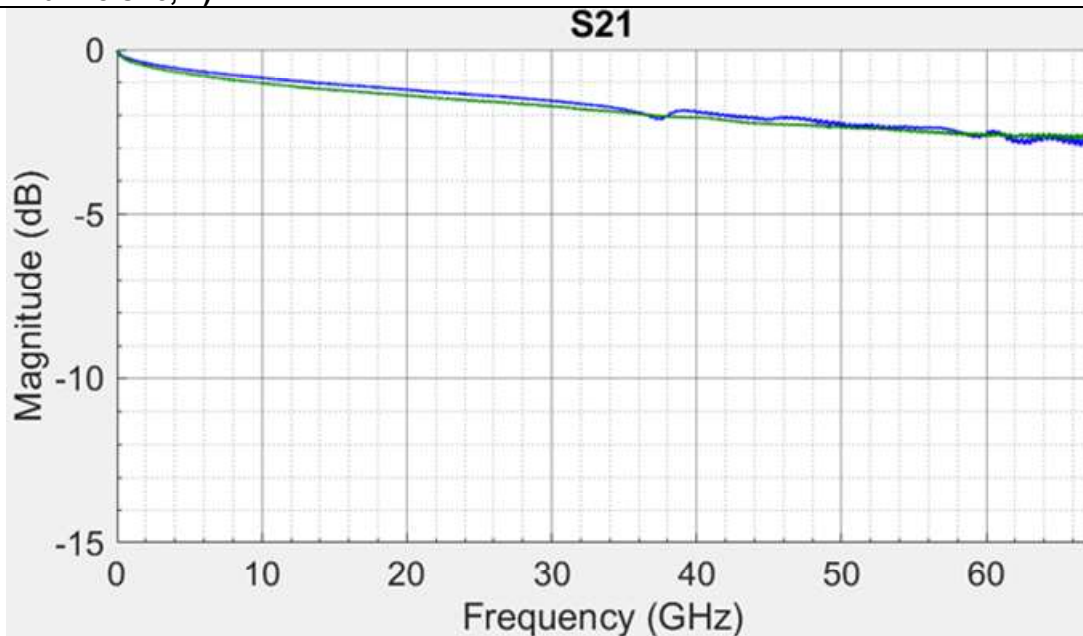
HC2 Adaptor Testing Procedure



11.0 SIGNAL INTEGRITY RESULTS (HC2 1.85MM RF ADAPTOR #1)

Insertion Loss (S21), Single-Ended

(CoreHC Channels: 3, 4)

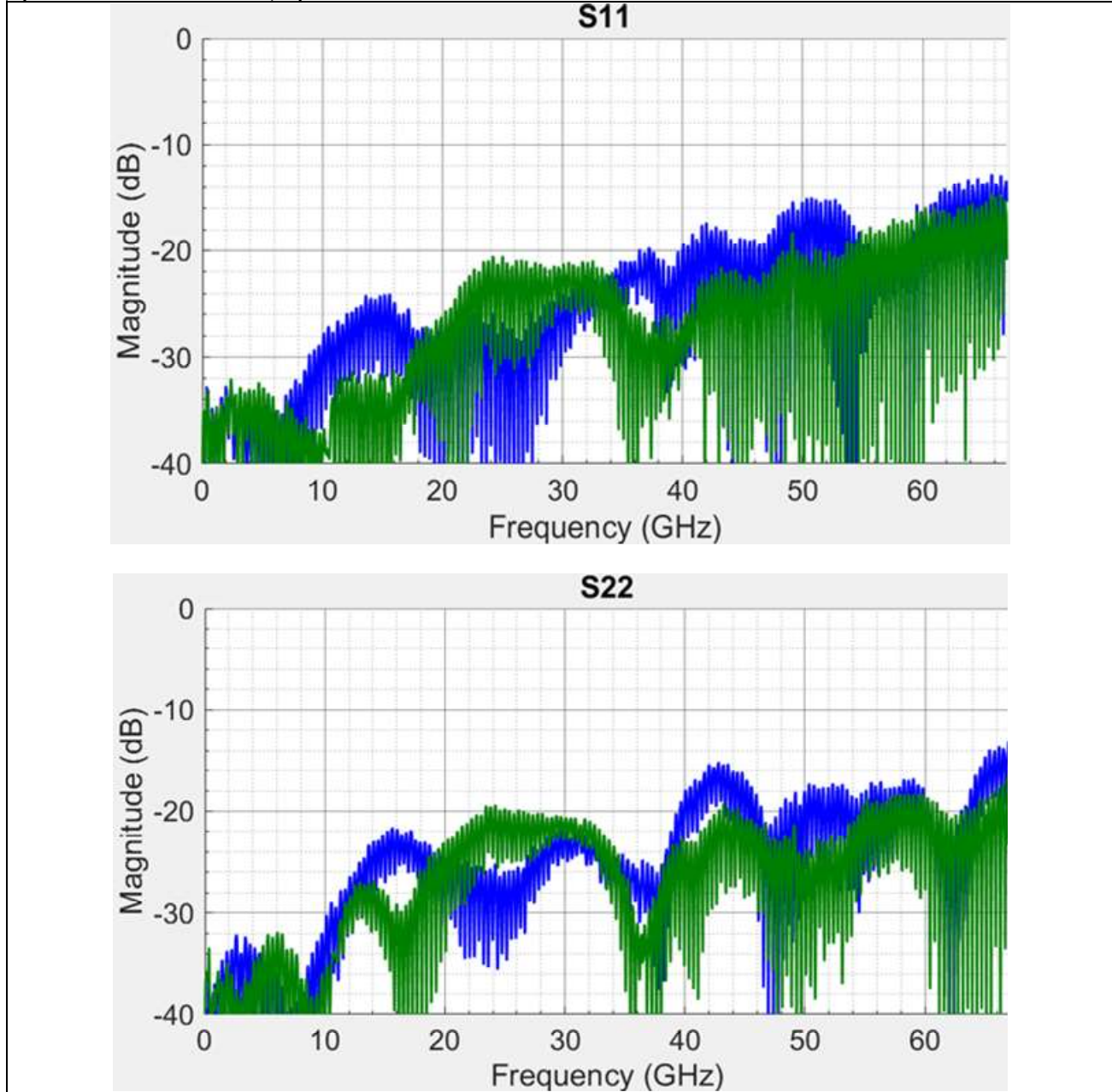


REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/12/2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 20 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			

SIGNAL INTEGRITY REPORT

Return Loss (S11, S22), Single-Ended

(CoreHC Channels: 3, 4)



12.0 APPENDIX, (SPARAMETERS SHOWN IN REPORT)

CoreHC Reference Cable Assembly_SIW_2-Position Measurements_041221 4/12/2021 7:54 PM Compressed (zipp... 5,145 KB

REVISION: 1	ECN INFORMATION: EC No: N/A DATE: 04/12/2021	TITLE: Core HC 2.5mm SIW: Configuration 1X2P (HC2 to PCB) CARLISLE IT CONFIDENTIAL	SHEET No. 21 of 21
DOCUMENT NUMBER: RSI-TM7SSSH22S8MS028	SI ENGINEER: R.Stavoli	DESIGN ENGINEER H.Tran	ENGINEERING MANAGER E.Soubh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			